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Team Nexperia

# 74CBTLV3125

## 4-bit bus switch

Rev. 4 — 9 November 2016

Product data sheet

## 1. General description

The 74CBTLV3125 provides a 4-bit high-speed bus switch with separate output enable inputs (1OE to 4OE). The low on-state resistance of the switch allows connections to be made with minimal propagation delay. The switch is disabled (high-impedance OFF-state) when the output enable (nOE) input is HIGH.

To ensure the high-impedance OFF-state during power-up or power-down, nOE should be tied to the V<sub>CC</sub> through a pull-up resistor. The minimum value of the resistor is determined by the current-sinking capability of the driver.

Schmitt trigger action at control input makes the circuit tolerant to slower input rise and fall times across the entire V<sub>CC</sub> range from 2.3 V to 3.6 V.

This device is fully specified for partial power-down applications using I<sub>OFF</sub>. The I<sub>OFF</sub> circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

- Supply voltage range from 2.3 V to 3.6 V
- Standard '125'-type pinout
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
  - ◆ CDM AEC-Q100-011 revision B exceeds 1000 V
- 5 Ω switch connection between two ports
- Rail to rail switching on data I/O ports
- CMOS low power consumption
- Latch-up performance exceeds 250 mA per JESD78B Class I level A
- I<sub>OFF</sub> circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from -40 °C to +85 °C and -40 °C to +125 °C



### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74CBTLV3125DS	-40 °C to +125 °C	SSOP16 <sup>[1]</sup>	plastic shrink small outline package; 16 leads; body width 3.9 mm; lead pitch 0.635 mm	SOT519-1
74CBTLV3125PW	-40 °C to +125 °C	TSSOP14	plastic thin shrink small outline package; 14 leads; body width 4.4 mm	SOT402-1
74CBTLV3125BQ	-40 °C to +125 °C	DHVQFN14	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm	SOT762-1

[1] Also known as QSOP16.

### 4. Functional diagram

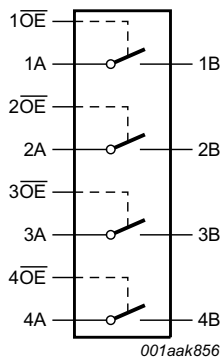


Fig 1. Logic symbol

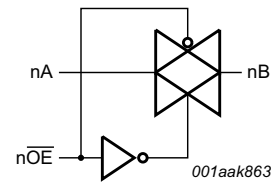
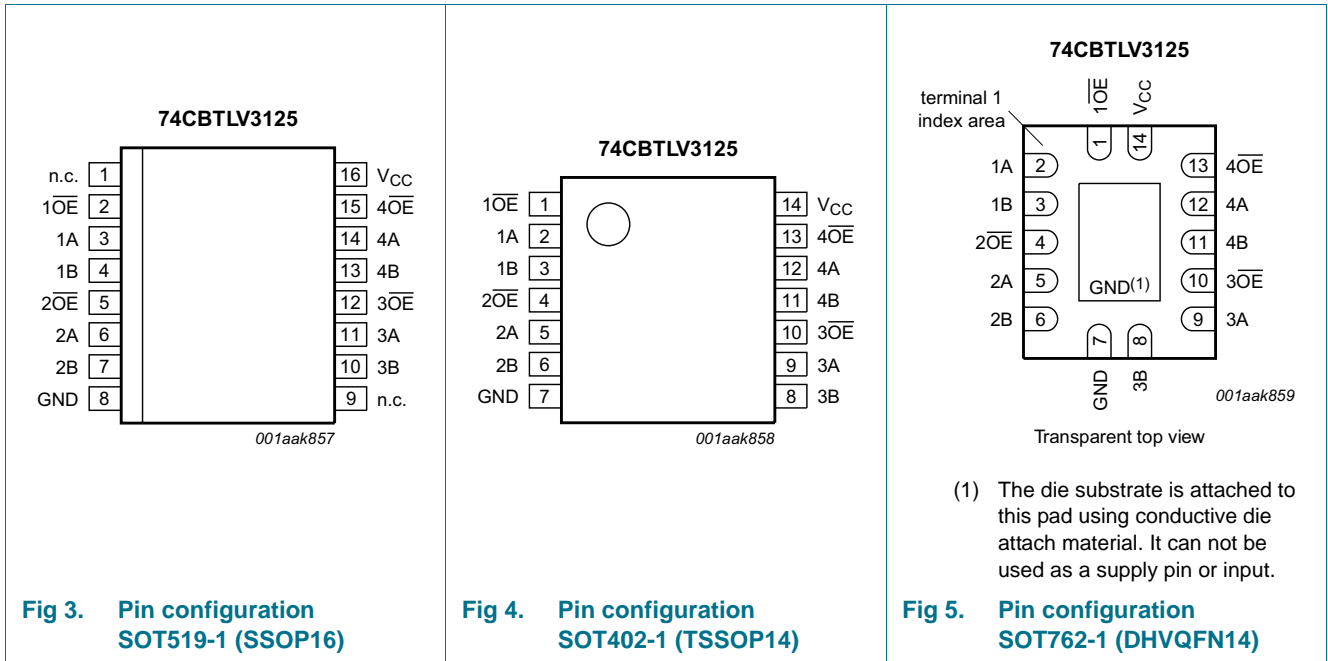


Fig 2. Logic diagram (one switch)

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin		Description
	SOT519-1	SOT402-1 and SOT762-1	
1OE, 2OE, 3OE, 4OE	2, 5, 12, 15	1, 4, 10, 13	output enable input
1A, 2A, 3A, 4A,	3, 6, 11, 14	2, 5, 9, 12	A input/output
1B, 2B, 3B, 4B	4, 7, 10, 13	3, 6, 8, 11	B output/input
GND	8	7	ground (0 V)
VCC	16	14	positive supply voltage
n.c.	1, 9	-	not connected

6. Functional description

Table 3. Function table<sup>[1]</sup>

Output enable input OE	Function switch
L	ON-state
H	OFF-state

[1] H = HIGH voltage level; L = LOW voltage level.

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+4.6	V
V <sub>I</sub>	input voltage	control inputs <a href="#">[1]</a>	-0.5	+4.6	V
V <sub>SW</sub>	switch voltage	enable and disable mode <a href="#">[2]</a>	-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V	-50	-	mA
I <sub>SK</sub>	switch clamping current	V <sub>I</sub> < -0.5 V	-50	-	mA
I <sub>SW</sub>	switch current	V <sub>SW</sub> = 0 V to V <sub>CC</sub>	-	±128	mA
I <sub>CC</sub>	supply current		-	+100	mA
I <sub>GND</sub>	ground current		-100	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C <a href="#">[3]</a>	-	500	mW

[1] The minimum input voltage rating may be exceeded if the input clamping current ratings are observed.

[2] The switch voltage ratings may be exceeded if switch clamping current ratings are observed

[3] For SSOP16 and TSSOP14 packages: P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.  
For DHVQFN14 packages: P<sub>tot</sub> derates linearly with 4.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		2.3	3.6	V
V <sub>I</sub>	input voltage	control inputs	0	3.6	V
V <sub>SW</sub>	switch voltage	enable and disable mode	0	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+125	°C
Δt/ΔV	input transition rise and fall rate	pin n $\overline{O}E$ ; V <sub>CC</sub> = 2.3 V to 3.6 V	0	200	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ <a href="#">[1]</a>	Max	Min	Max	
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7	-	-	1.7	-	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	2.0	-	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	-	-	0.7	-	0.7	V
		V <sub>CC</sub> = 3.0 V to 3.6 V	-	-	0.9	-	0.9	V
I <sub>I</sub>	input leakage current	pin n $\overline{O}E$ ; V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 3.6 V	-	-	±1.0	-	±20	μA
I <sub>S(OFF)</sub>	OFF-state leakage current	V <sub>CC</sub> = 3.6 V; see <a href="#">Figure 6</a>	-	-	±1	-	±20	μA

**Table 6. Static characteristics ...continued**

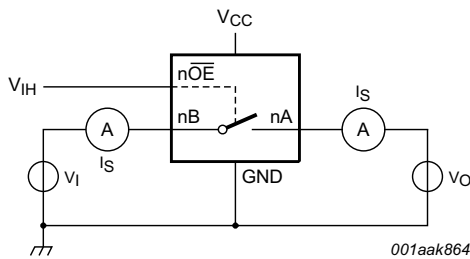
At recommended operating conditions voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = -40 °C to +85 °C			T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
I <sub>S(ON)</sub>	ON-state leakage current	V <sub>CC</sub> = 3.6 V; see <a href="#">Figure 7</a>	-	-	±1	-	±20	μA
I <sub>OFF</sub>	power-off leakage current	V <sub>I</sub> or V <sub>O</sub> = 0 V to 3.6 V; V <sub>CC</sub> = 0 V	-	-	±10	-	±50	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A; V <sub>SW</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 3.6 V	-	-	10	-	50	μA
ΔI <sub>CC</sub>	additional supply current	pin n $\overline{\text{OE}}$ ; V <sub>I</sub> = V <sub>CC</sub> - 0.6 V; <sup>[2]</sup> V <sub>SW</sub> = GND or V <sub>CC</sub> ; V <sub>CC</sub> = 3.6 V	-	-	300	-	2000	μA
C <sub>I</sub>	input capacitance	pin n $\overline{\text{OE}}$ ; V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = 0 V to 3.3 V	-	0.9	-	-	-	pF
C <sub>S(OFF)</sub>	OFF-state capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = 0 V to 3.3 V	-	5.2	-	-	-	pF
C <sub>S(ON)</sub>	ON-state capacitance	V <sub>CC</sub> = 3.3 V; V <sub>I</sub> = 0 V to 3.3 V	-	14.3	-	-	-	pF

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.

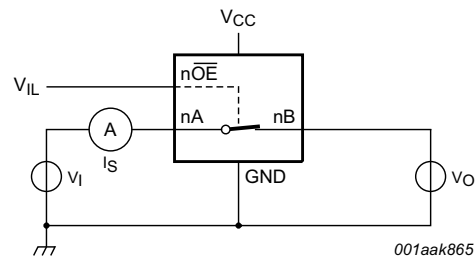
[2] One input at 3 V, other inputs at V<sub>CC</sub> or GND.

### 9.1 Test circuits



V<sub>I</sub> = V<sub>CC</sub> or GND and V<sub>O</sub> = GND or V<sub>CC</sub>.

**Fig 6. Test circuit for measuring OFF-state leakage current (one switch)**



V<sub>I</sub> = V<sub>CC</sub> or GND and V<sub>O</sub> = open circuit.

**Fig 7. Test circuit for measuring ON-state leakage current (one switch)**

9.2 ON resistance

Table 7. Resistance  $R_{ON}$

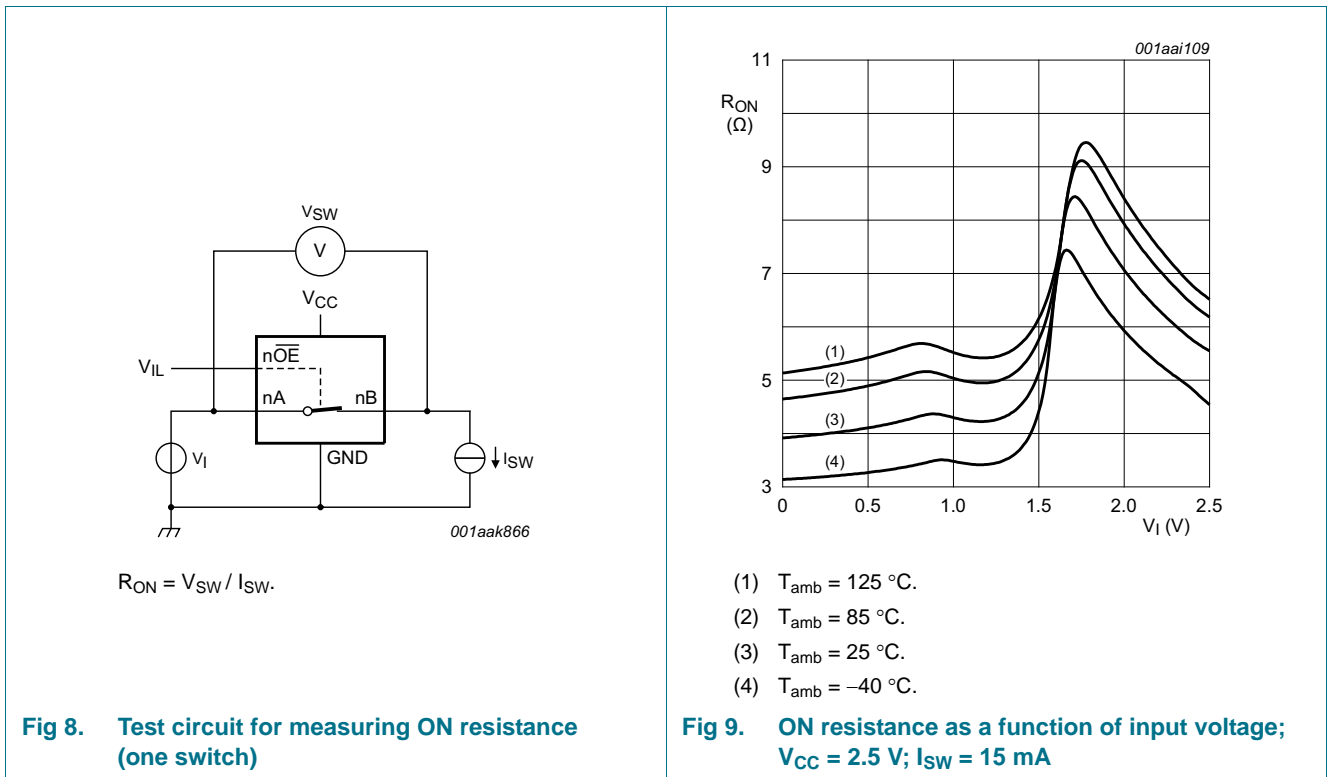
At recommended operating conditions; voltages are referenced to GND (ground = 0 V); for test circuit see Figure 8.

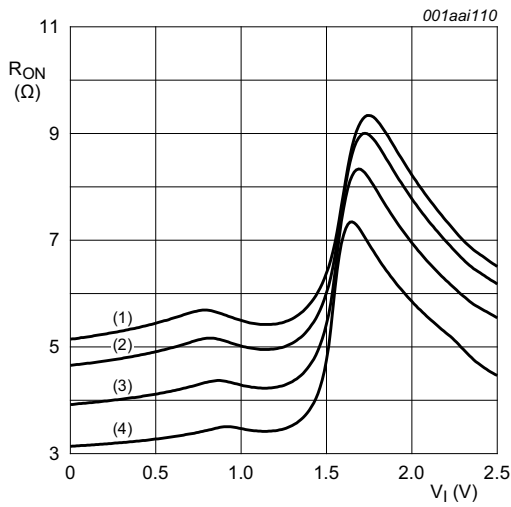
Symbol	Parameter	Conditions	$T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C to }+125\text{ }^{\circ}\text{C}$		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$R_{ON}$	ON resistance	$V_{CC} = 2.3\text{ V to }2.7\text{ V};$ see Figure 9 to Figure 11 <sup>[2]</sup>						
		$I_{SW} = 64\text{ mA}; V_I = 0\text{ V}$	-	4.2	8.0	-	15.0	$\Omega$
		$I_{SW} = 24\text{ mA}; V_I = 0\text{ V}$	-	4.2	8.0	-	15.0	$\Omega$
		$I_{SW} = 15\text{ mA}; V_I = 1.7\text{ V}$	-	8.4	40.0	-	60.0	$\Omega$
		$V_{CC} = 3.0\text{ V to }3.6\text{ V};$ see Figure 12 to Figure 14						
		$I_{SW} = 64\text{ mA}; V_I = 0\text{ V}$	-	4.0	7.0	-	11.0	$\Omega$
		$I_{SW} = 24\text{ mA}; V_I = 0\text{ V}$	-	4.0	7.0	-	11.0	$\Omega$
		$I_{SW} = 15\text{ mA}; V_I = 2.4\text{ V}$	-	6.2	15.0	-	25.5	$\Omega$

[1] Typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$  and nominal  $V_{CC}$ .

[2] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

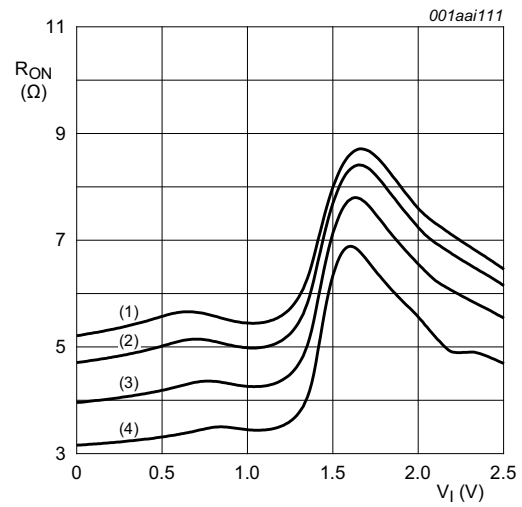
9.3 ON resistance test circuit and graphs





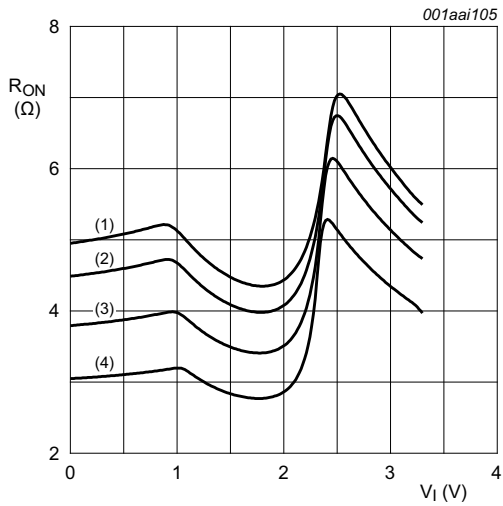
- (1)  $T_{amb} = 125\text{ }^{\circ}\text{C}.$
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}.$
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}.$
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}.$

**Fig 10. ON resistance as a function of input voltage;**  
 $V_{CC} = 2.5\text{ V}; I_{SW} = 24\text{ mA}$



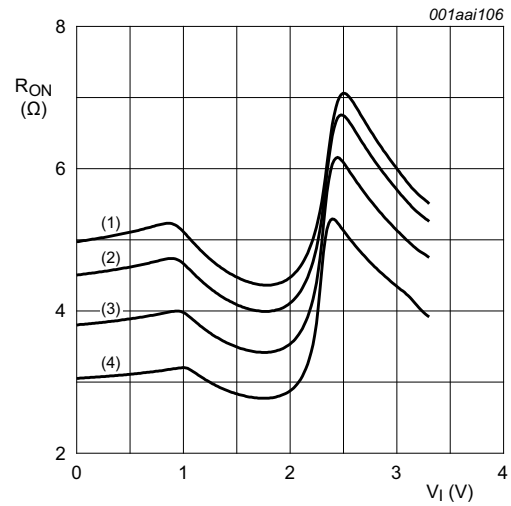
- (1)  $T_{amb} = 125\text{ }^{\circ}\text{C}.$
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}.$
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}.$
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}.$

**Fig 11. ON resistance as a function of input voltage;**  
 $V_{CC} = 2.5\text{ V}; I_{SW} = 64\text{ mA}$



- (1)  $T_{amb} = 125\text{ }^{\circ}\text{C}.$
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}.$
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}.$
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}.$

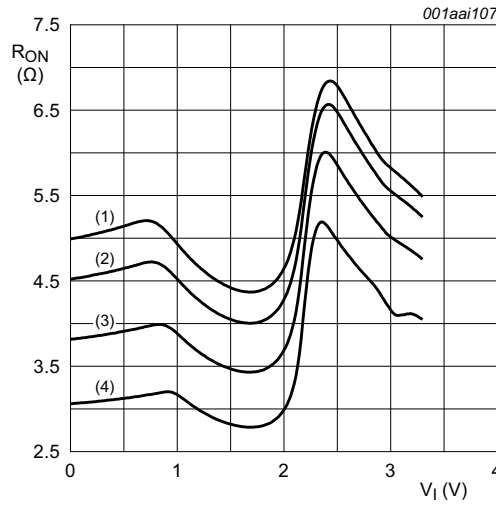
**Fig 12. ON resistance as a function of input voltage;**  
 $V_{CC} = 3.3\text{ V}; I_{SW} = 15\text{ mA}$



- (1)  $T_{amb} = 125\text{ }^{\circ}\text{C}.$
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}.$
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}.$
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}.$

**Fig 13. ON resistance as a function of input voltage;**  
 $V_{CC} = 3.3\text{ V}; I_{SW} = 24\text{ mA}$





- (1)  $T_{amb} = 125\text{ }^{\circ}\text{C}$ .
- (2)  $T_{amb} = 85\text{ }^{\circ}\text{C}$ .
- (3)  $T_{amb} = 25\text{ }^{\circ}\text{C}$ .
- (4)  $T_{amb} = -40\text{ }^{\circ}\text{C}$ .

Fig 14. ON resistance as a function of input voltage;  $V_{CC} = 3.3\text{ V}$ ;  $I_{SW} = 64\text{ mA}$

## 10. Dynamic characteristics

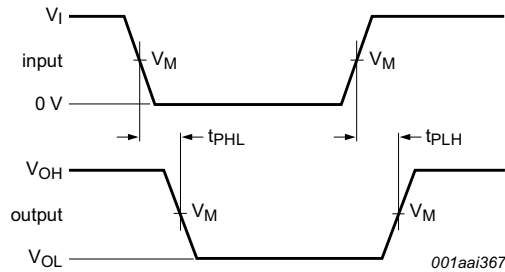
Table 8. Dynamic characteristics

$GND = 0\text{ V}$ ; for test circuit see Figure 17

Symbol	Parameter	Conditions	$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C to } +125\text{ }^{\circ}\text{C}$		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$t_{pd}$	propagation delay	nA to nB or nB to nA; see Figure 15 <sup>[2][3]</sup>						
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	-	-	0.13	-	0.20	ns
		$V_{CC} = 3.0\text{ V to } 3.6\text{ V}$	-	-	0.20	-	0.31	ns
$t_{en}$	enable time	$\overline{nOE}$ to nA or nB; see Figure 16 <sup>[4]</sup>						
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	1.0	2.7	4.6	1.0	6.0	ns
		$V_{CC} = 3.0\text{ V to } 3.6\text{ V}$	1.0	2.4	4.4	1.0	6.0	ns
$t_{dis}$	disable time	$\overline{nOE}$ to nA or nB; see Figure 16 <sup>[5]</sup>						
		$V_{CC} = 2.3\text{ V to } 2.7\text{ V}$	1.0	2.2	3.9	1.0	5.5	ns
		$V_{CC} = 3.0\text{ V to } 3.6\text{ V}$	1.0	2.9	4.2	1.0	5.5	ns

- [1] All typical values are measured at  $T_{amb} = 25\text{ }^{\circ}\text{C}$  and at nominal  $V_{CC}$ .
- [2] The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the load capacitance, when driven by an ideal voltage source (zero output impedance).
- [3]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .
- [4]  $t_{en}$  is the same as  $t_{PZH}$  and  $t_{PZL}$ .
- [5]  $t_{dis}$  is the same as  $t_{PHZ}$  and  $t_{PLZ}$ .

11. Waveforms

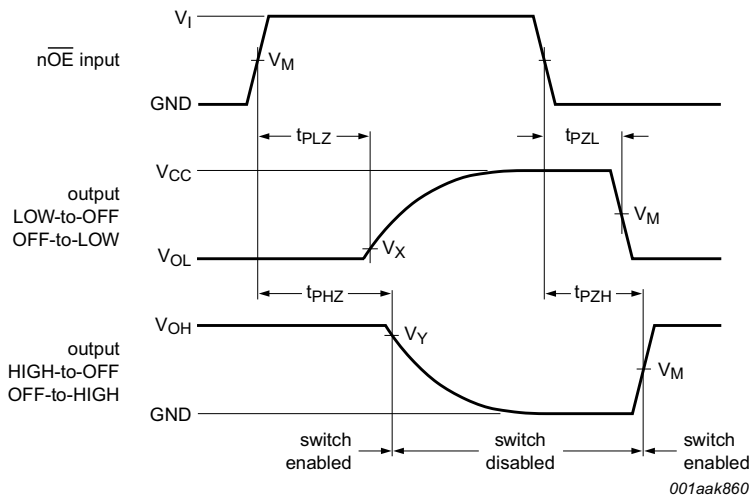


Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 15. The data input (nA or nB) to output (nB or nA) propagation delays**

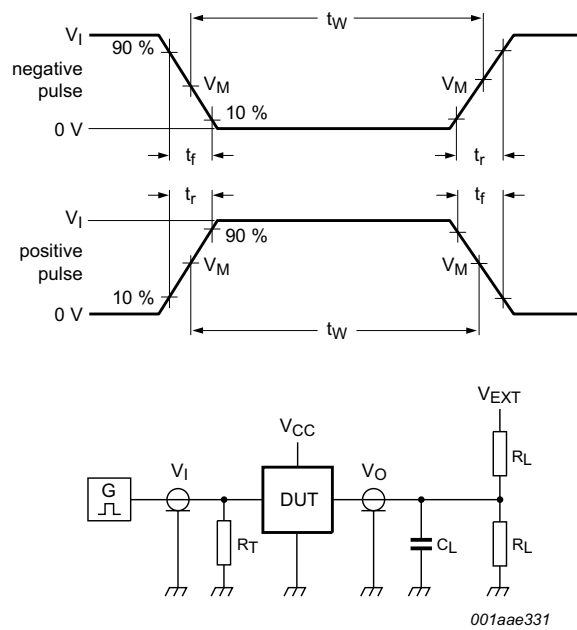
**Table 9. Measurement points**

Supply voltage	Input			Output		
$V_{CC}$	$V_M$	$V_I$	$t_r = t_f$	$V_M$	$V_X$	$V_Y$
2.3 V to 2.7 V	$0.5V_{CC}$	$V_{CC}$	$\leq 2.0$ ns	$0.5V_{CC}$	$V_{OL} + 0.15$ V	$V_{OH} - 0.15$ V
3.0 V to 3.6 V	$0.5V_{CC}$	$V_{CC}$	$\leq 2.0$ ns	$0.5V_{CC}$	$V_{OL} + 0.3$ V	$V_{OH} - 0.3$ V



Measurement points are given in [Table 9](#).  
 Logic levels:  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 16. Enable and disable times**



Test data is given in [Table 10](#).

Definitions for test circuit:

$R_L$  = Load resistance.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_T$  = Termination resistance should be equal to the output impedance  $Z_o$  of the pulse generator.

$V_{EXT}$  = External voltage for measuring switching times.

**Fig 17. Test circuit for measuring switching times**

**Table 10. Test data**

Supply voltage	Load		$V_{EXT}$
$V_{CC}$	$C_L$	$R_L$	$t_{PLH}, t_{PHL}$ $t_{PZH}, t_{PHZ}$ $t_{PZL}, t_{PLZ}$
2.3 V to 2.7 V	30 pF	500 $\Omega$	open    GND $2V_{CC}$
3.0 V to 3.6 V	50 pF	500 $\Omega$	open    GND $2V_{CC}$

### 11.1 Additional dynamic characteristics

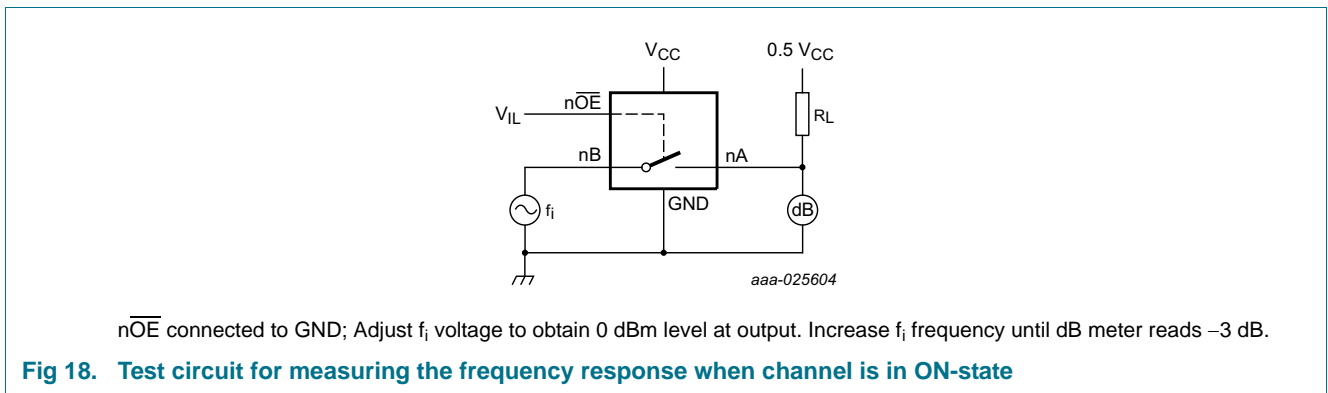
**Table 11. Additional dynamic characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V);  $V_I = GND$  or  $V_{CC}$  (unless otherwise specified);  $t_r = t_f \leq 2.5$  ns.

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			Unit
			Min	Typ	Max	
f <sub>(-3dB)</sub>	-3 dB frequency response	V <sub>CC</sub> = 3.3 V; R <sub>L</sub> = 50 Ω; see <a href="#">Figure 18</a> [1]	-	406	-	MHz

[1] f<sub>i</sub> is biased at 0.5V<sub>CC</sub>.

### 11.2 Test circuit



12. Package outline

SSOP16: plastic shrink small outline package; 16 leads; body width 3.9 mm; lead pitch 0.635 mm SOT519-1

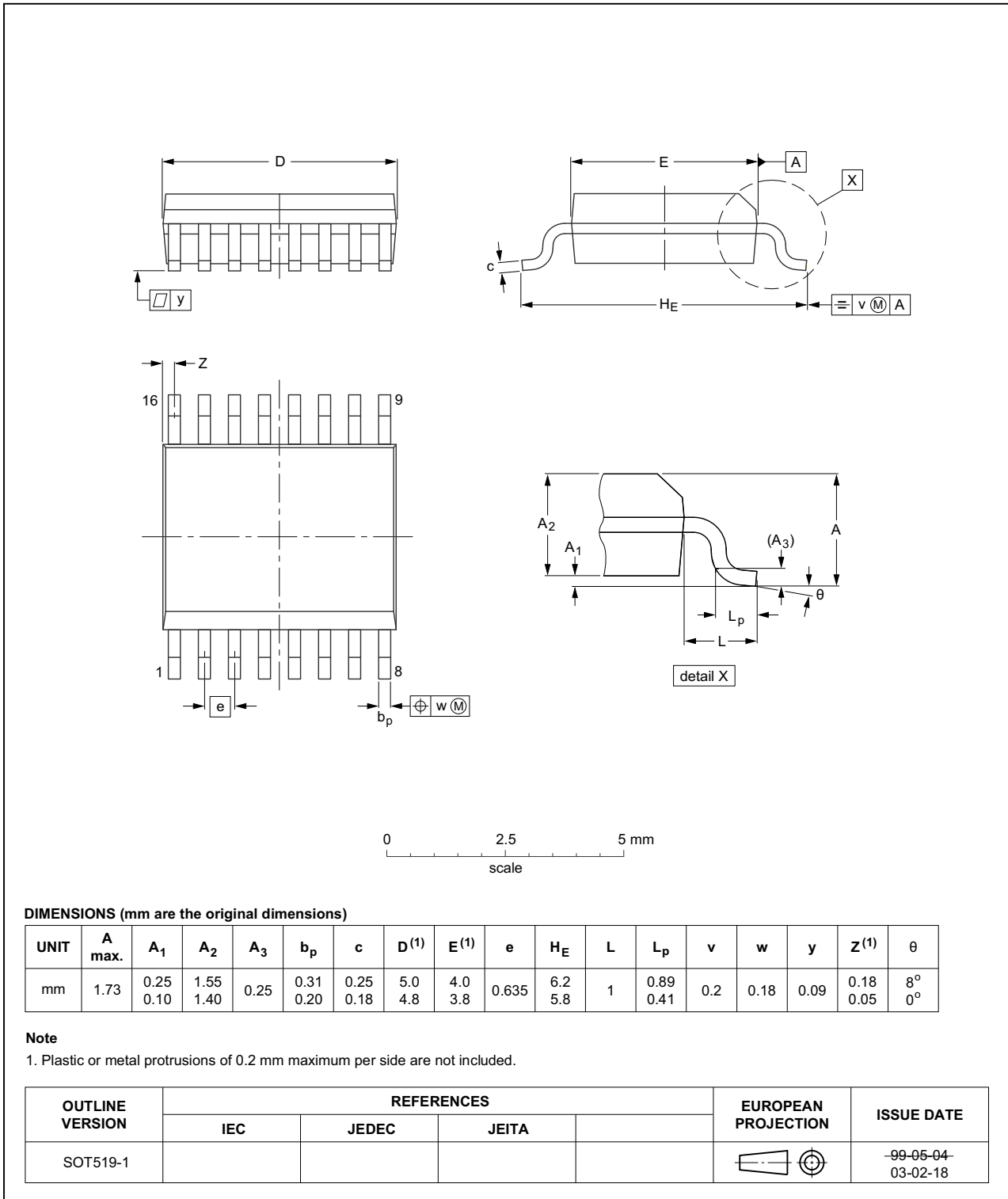


Fig 19. Package outline SOT519-1 (SSOP16)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

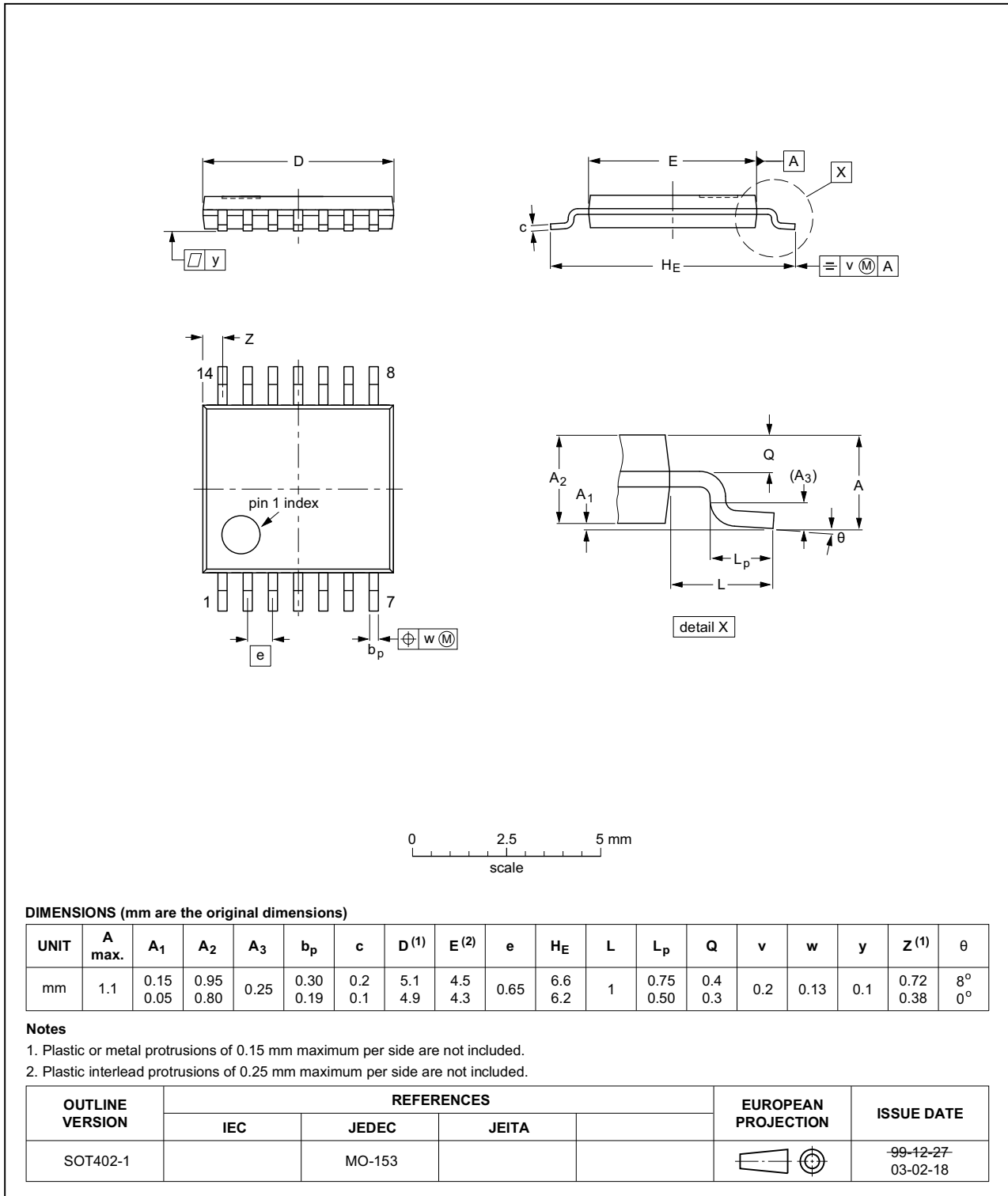


Fig 20. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

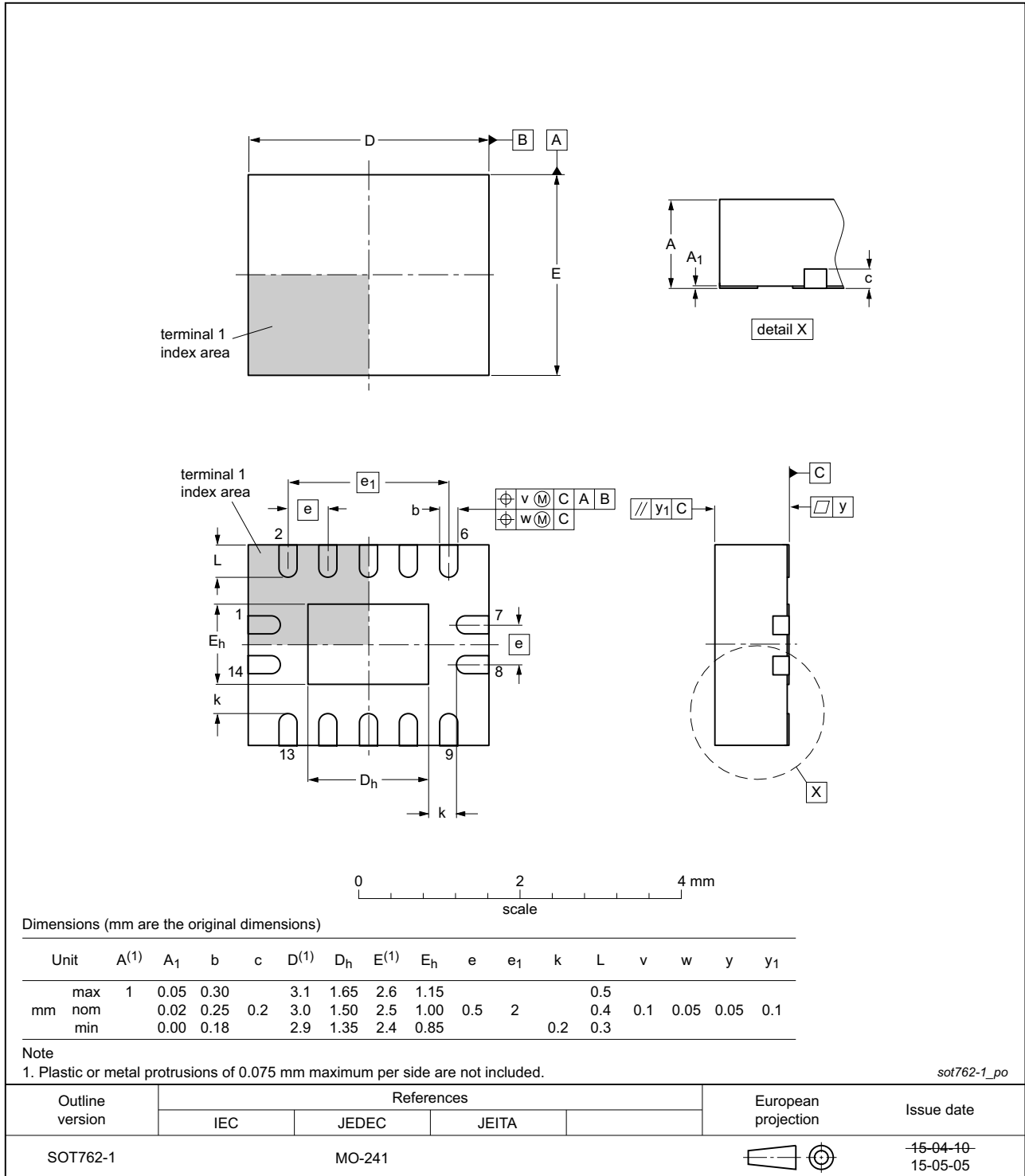


Fig 21. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 14. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74CBTLV3125 v.4	20161109	Product data sheet	-	74CBTLV3125 v.3
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Section 11.1</a> and <a href="#">Section 11.2</a> added.</li> </ul>			
74CBTLV3125 v.3	20111215	Product data sheet	-	74CBTLV3125 v.2
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74CBTLV3125 v.2	20110104	Product data sheet	-	74CBTLV3125 v.1
74CBTLV3125 v.1	20100108	Product data sheet	-	-



## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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